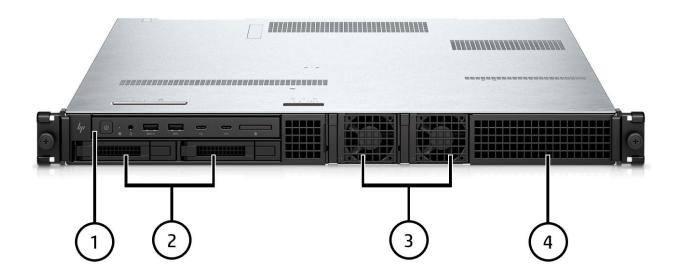
Overview

HP Z4 Rack G5 Workstation



Front view

1. Front I/O Premium (optional – show above)1:

Power Button

Headphone/microphone combo

- 2 x SuperSpeed USB Type-A 5 Gbps signalling rate [left-most Type-A port supports BC1.2 (Battery Charging)]
- 2 x SuperSpeed USB Type-C™ 20 Gbps signalling rate (USB Power Delivery 3.0),

Front I/O Entry:

Power Button

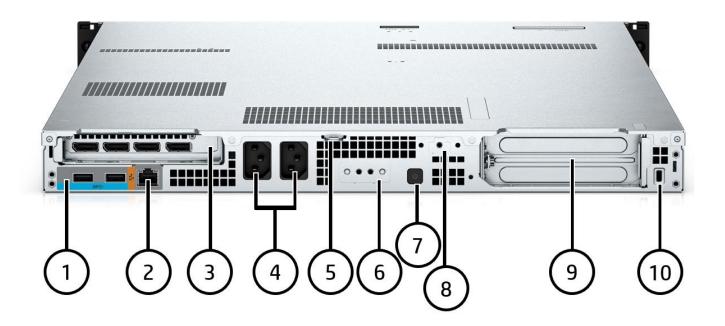
Headphone/microphone combo

4 x SuperSpeed USB Type-A 5 Gbps signalling rate [left-most Type-A ports supports BC1.2 (Battery Charging)]

- 2. 2 x 2.5" external drive bays for front-accessible NVMe storage
- 3. 2 x external 675W PSU bays (system can be configured with a single PSU or with dual PSUs configured in either Redundant or Aggregate Mode)
- 4. 1 x 3.5" drive bay (can be configured 1 x 3.5" Enterprise HDD or with 2 x M.2 drives via the HP 3.5 in Drive Cage Adapter)

¹ Front I/O Premium requires both 675W PSUs to be configured

Overview



Rear View

- 1. 2 x SuperSpeed USB Type-A 5 Gbps signalling rate
- 2. 1 x 1GbE RJ-45 (Intel® AMT enabled)
- 3. Single Slot Riser (1 PCle Gen5 x16) **NOTE:** DisplayPorts do not come standard¹
- 4. Primary (left) and secondary (right) power supply cable connectors
- 5. Padlock loop
- 6. Flex I/O Module (optional)
- 7. Rear Power Button
- 8. Z Desktop Power and Signal Interface (optional configured for use with the HP Remote System Controller)
- Dual Slot Riser (1 PCIe Gen5 x16 mechanical (x16/x8 electrical); 1 PCIe 5 x16 mechanical (x8 electrical)²
- 10. Kensington Lock Slot

²The Dual Slot Riser is optional, but required for double wide graphics cards and configurations with more than one PCIe

¹ The ports in the Single Slot Riser are dependent on the PCIe card that is configured there

Supported Components

Overview

Form Factor Operating Systems

1U Rackable Workstation

Preinstalled:

- Windows 11 Pro for Workstations¹
- Ubuntu Linux 22.04
- HP Linux®-ready (minimal OS ready for customer OS installation)^{3,4}

License Only:

 Red Hat® Enterprise Linux® Desktop Workstation (includes paper license with 1 year support; no preinstalled OS)⁴

Supported:

- Windows 11, version 22H2, 21H2¹
- Windows 10, version 22H2, 21H2¹
- Red Hat® Enterprise Linux® Workstation 8 & 9⁴
- SUSE Linux® Enterprise Desktop 15⁴
- Ubuntu 20.04 & 22.04 LTS^{3,4}

Web-supported only:

- Windows 11 Enterprise^{1,5}
- Windows 10 Enterprise^{1,5}

http://www.hp.com/support/linux hardware matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software, or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply, and additional requirements may apply over time for updates. See http://www.windows.com.

³A certified preloaded version of Ubuntu[®] 20.04 LTS is available from HP for this platform.

⁴For detailed Linux[®] OS/hardware support information, see:

⁵ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.

Supported Components

				Frequenc (GHz)	У			ory Speed (/s)	
Name ¹	Cores	Threads	Base Clock Speed	Intel® Turbo Boost Max All-Core Frequency ²	Intel® Turbo Boost Max Single-Core Frequency ²	Cache (MB)	1 DIMM per Channel	2 DIMM per Channel	TDP (W)
Intel® Xeon® W7-2495X	24	48	2.5	3.3	4.6	45	4800	4400	225
Intel® Xeon® W7-2475X	20	40	2.6	3.4	4.6	37.5	4800	4400	225
Intel® Xeon® W5-2465X	16	32	3.1	3.7	4.5	33.75	4800	4400	200
Intel® Xeon® W5-2455X	12	24	3.2	3.9	4.4	30	4800	4400	200
Intel® Xeon® W5-2445	10	20	3.1	4.0	4.4	26.25	4800	4400	175
Intel® Xeon® W3-2435	8	16	3.1	4.0	4.3	22.5	4400	4400	165
Intel® Xeon® W3-2425	6	12	3.0	3.7	4.2	15	4400	4400	130
Intel® Xeon® W3-2423	6	12	2.1	3.1	4.0	15	4400	4400	120

Notes:

- Xeon W-2400 processors all feature Intel® vPro® Technology³
- Xeon W-2400 processors all support Hyper-Threading
- Xeon W-2400 processors do not offer integrated graphics

³ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro



¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel Turbo Boost Max (ITBM) performance varies depending on hardware, software, and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

Supported Components

Expansion Slots (see system

Slot 1 (SSR1): PCI Express Gen5 x16 from CPU

board section for more details) Slot 2 (DSR2): PCI Express Gen5 x16 from CPU - operates as x8 if Slot 3 is loaded

Slot 3 (DSR): PCI Express Gen5 x16 (wired as x8) from CPU

M.2 Slot 1: PCI Express Gen4 x4 from CPU **M.2 Slot 2:** PCI Express Gen4 x4 from CPU

¹SSR = Single slot riser. Includes single 6+2 pin auxiliary power cable

² DSR = Dual slot riser. DSR is optional but required for double wide graphics cards and

configurations with more than one PCI card. DSR includes and additional dual 6+2 pin auxiliary

power cable

Expansion Bays (see storage

section for more details)

2 external 2.5" bays

1 external 3.5" bay (can be configured with 1 x 3.5" hard drive or 2 x 2.5" adapter for supporting

2 additional M.2 drives)

Front I/O Premium:¹ 2 SuperSpeed USB Type-C™ 20 Gbps signaling rate (USB Power Delivery

3.0), 2 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo. [left-

most Type-A ports supports BC1.2 (Battery Charging)]

Front I/O Entry: 4 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone

combo. [left-most Type-A ports supports BC1.2 (Battery Charging)]

Front I/O Premium requires both 675W PSUs to be configured

Internal I/O 3 Internal USB ports and 1 SATA 3 port

Rear I/O 2x USB 3.1 G1 Type-A

1x 1GbE LAN port (supporting Intel AMT)

Optional I/O Flex I/O Module (Serial Port v3, 10GbE single port, 2.5GbE LAN single port, 1 GbE Fiber LC NIC)

Z Desktop Power and Signal Interface for supporting the HP Remote System Controller

Chassis Dimensions

Base footprint without front bezel and rack brackets (H x W

x D)

H: 1.685" (43mm) W: 17.25" (438mm) D: 25.8" (654mm)

With front bezel and rack

brackets (H x W x D)

H: 1.685" (43mm) W: 18.96" (487mm) D: 25.8" (675mm)

Packaged Dimensions H: 8.66" (220mm)

W: 23.23" (590mm) D: 35.43" (900mm)

Palletization Profile 2 units per layer x 8 layers = 16 units per pallet

1200x1000x1890mm (included pallet)

Rack Dimensions 1U

Weight Exact weights depend upon configuration (System weight only).

Minimum: 9.52kg (21.6lb) Standard: 11.7kg (25.8lb) Maximum: 12.1kg (26.7lb)

Temperature Operating: 5° to 40°C (40° to 104°F)¹

Non-operating: -40° to 60°C (-40° to 140°F)

¹40°C has been validated for (add configuration information)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C

(1.8° F) for every 305 m (1,000 feet) increase in elevation

Maximum rate of change: 10 °C/hr No direct sustained sunlight

Supported Components

Humidity Operating: 8% to 85% relative humidity, non-condensing, 35° C maximum wet bulb

Non-operating: 8% to 90% relative humidity, non-condensing, 35° C maximum wet bulb

Maximum Altitude (nonpressurized) Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See Temperature for details.

Power Supply The Z4 Rack G5 675W power supply efficiency report can be found at this link:

https://www.clearesult.com/80plus/

ENTRY

Contains one (1) PSU 675W power supply.

ENTRY REDUNDANT

Contains two (2) 675W PSUs operating in redundant mode for a maximum system

power of 675W.

NOTE: All power cords supplied by HP for Desktop Workstations are between 1.83m and 2.5m

(dependent on country localization and platform)."

HIGH-END

Contains two (2) 675W PSUs operating in aggregate mode for a total system power of

1350W (2x675W).

Workstation ISV Certifications See the latest list of certifications at

http://www8.hp.com/us/en/campaigns/workstations/industries-and-partners.html

Chipset Intel® W790 chipset

Memory 4 DIMM slots, supporting up to 256GB, DDR5 4800 MT/s speed depending on the system

configuration

Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-2400 Processors				
	Intel® Xeon® W7-2495X	Υ	N		
	Intel® Xeon® W7-2475X	Υ	N		
	Intel® Xeon® W5-2465X	Υ	N		
	Intel® Xeon® W5-2455X	Υ	N		
	Intel® Xeon® W5-2445	Υ	N		
	Intel® Xeon® W3-2435	Υ	N		
	Intel® Xeon® W3-2425	Υ	N		
	Intel® Xeon® W3-2423	Υ	N		

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	1TB 7200RPM SATA 3.5in Enterprise HDD ¹	Υ	Υ	WOR10AA
	2TB 7200RPM SATA 3.5in Enterprise HDD ¹	Υ	Υ	2Z274AA
	4TB 7200 RPM SATA 3.5in Enterprise HDD ¹	Υ	Υ	K4T76AA/AT
	8TB 7200RPM SATA 3.5in Enterprise HDD ¹	Υ	Υ	2Z273AA
	12TB 7200 RPM SATA-6G 3.5in Enterprise HDD ¹	Υ	Υ	5S461AA

PCIe Solid State Drives

Z Turbo 512GB PCIe-4x4 TLC SSD Module	Υ	Υ	38T80AA
Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T81AA
Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T76AA
Z Turbo 1TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T77AA
Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T79AA
Z Turbo 2TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T75AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module	Υ	Υ	5S496AA/AT
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	5S497AA/AT
HP Z Turbo Drive Dual Pro			
HP Z Turbo Drive Dual Pro PCIe-4x4 NVMe Carrier ²	Υ	Υ	56Q86AA
Intel® Virtual RAID on CPU (Intel® VROC) for NVMe			
Intel VROC NVMe SSD Premium Ctlr Module ⁴	Υ	Υ	3FJ81AA
Intel VROC NVMe SSD Standard Ctlr Module ³	Υ	Υ	3FJ80AA

Note 1: Up to (1) 3.5-inch 7200 rpm SATA drive

Note 2: Kit includes Dual Pro carrier and heatsink. Requires separate purchase of ZTurbo PCIe 4x4 M.2 SSD modules.

Note 3: Enables RAID 0, 1 & 10

Note 4: Enables RAID 0, 1 & 10 plus RAID 5 with write hole closure options

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



Supported Components

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Graphics Cable	HP DisplayPort To VGA Adapter	N	Υ	AS615AA/AT	
Adapters	HP DisplayPort To VGA Adapter	N	Υ	F7W97AA	
	HP DisplayPort to HDMI Adapter	Υ	Υ	2JA63AA	
	HP (Bulk 12) miniDP-to-DP Adapter Cables	N	Υ	2KW87A6	
	HP Single miniDP-to-DP Adapter Cable	Υ	Υ	2MY05AA	
	HP miniDP-to-DP Adapter (2-pack)	Υ	N		
	HP miniDP-to-DP Adapter (4-pack)	Υ	N		
	HP DisplayPort to DVI Adapter	Υ	Υ	FH973AA	
Ultra-High-End	NVIDIA® RTX 6000 Ada 48GB ¹	Υ	Υ	79C23AA	1
Graphics	NVIDIA® RTX 6000 Ada 48 GB 4DP w/NVIDIA Omniverse Enterprise Graphics	N	Υ	9X3E1AA	1
	NVIDIA® RTX A6000 48GB 1	Υ	Υ	2S6U3AA/AT	1
	NVIDIA® RTX 5000 Ada 32GB ¹	Υ	Υ	8D6B6AA	1
	NVIDIA® RTX A5000 24GB 1	Υ	Υ	20X23AA/AT	1
High-End Graphic	s NVIDIA® RTX 4500 Ada 24GB ¹	Υ	Υ	8D6C1AA	1
	NVIDIA® RTX A4500 20GB 1	Υ	Υ	5S458AA/AT	1
	NVIDIA® RTX 4000 Ada 20GB	Υ	Υ	8D6B7AA	1
	NVIDIA® RTX A4000 16GB 1,2	Υ	Υ	20X24AA/AT	2
	AMD® Radeon™ Pro W7600 8GB	Υ	Υ	8D6B9AA	1
	AMD® Radeon™ Pro W7500 8GB	Υ	Υ	8D6C2AA	1
	AMD® Radeon™ Pro W6800 32GB ¹	Υ	Υ	340K7AA	1
Midrange	NVIDIA® RTX A2000 12GB ¹	Υ	Υ	5Z7D9AA/AT	1
Graphics	NVIDIA® T1000 8GB ²	Υ	Υ	5Z7D8AA/AT	1
Entry	NVIDIA® T400 4GB ²	Υ	Υ	5Z7EOAA/AT	1
	Note 1. Craphics sand requires both C7FW power	cupplies to be see	oficured		

Note 1: Graphics card requires both 675W power supplies to be configured.

Note 2: Dual graphics configuration is tested and supported by HP, but not configurable from the factory. The customer will be responsible for purchasing a second graphics card aftermarket and integrating it themselves.

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	16GB (1x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	32GB (2x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	32GB (1x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	64GB (4x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	64GB (2x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	64GB (1x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	128GB (4x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	128GB (2x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	256GB (4x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	After Market Options				
	16GB DDR5 (1x16GB) 4800 DIMM ECC REG Memory	Υ	Υ	340K1AA	
	32GB DDR5 (1x32GB) 4800 DIMM ECC REG Memory	Υ	Υ	340K2AA	
	64GB DDR5 (1x64GB) 4800 DIMM ECC REG Memory	Υ	Υ	340K3AA	

Supported Components

Multimedia and Factory Option Kit
Audio Devices Configured Option Kit Part Number

Integrated Realtek ALC3205-CG Audio

N

Υ



Supported Components

Internal and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
_	Z Turbo 512GB PCIe-4x4 TLC Z4 Rack Kit SSD	Υ	Υ	7K6A5AA	
	Z Turbo 512GB PCIe-4x4 SED OPAL2 TLC Z4 Rack Kit SSD	Υ	Υ	7K6A6AA	
	Z Turbo 1TB PCIe-4x4 SED OPAL2 TLC Z4 Rack Kit SSD	Υ	Υ	7K6A7AA	
	Z Turbo 1TB PCIe-4x4 TLC Z4 Rack Kit SSD	Υ	Υ	7K6A8AA	
	Z Turbo 2TB PCIe-4x4 TLC Z4 Rack Kit SSD	Υ	Υ	7K6A9AA	
	Z Turbo 2TB PCIe-4x4 SED OPAL2 TLC Z4 Rack Kit SSD	Υ	Υ	7K6B0AA	
	Z Turbo 4TB PCIe-4x4 TLC Z4 Rack Kit SSD	Υ	Υ	7K6B1AA	
	Z Turbo 4TB PCIe-4x4 SED OPAL2 TLC Z4 Rack Kit SSD	Y	Υ	7K6B2AA	
Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 10GBase-T Flex Port	Υ	Υ	56Q71AA	
	HP 2.5GbE LAN Flex Port	Υ	Υ	169K0AA/AT	
	HP 1GbE Fiber LC Single Flex Port	Υ	Υ	20J15AA	
	Intel X550-T2 10GBASE-T Dual Port NIC	Υ	Υ	1QL46AA	
	Intel I225-T1 Single Port 2.5GbE PCIe NIC	Υ	Υ	406L9AA	
	Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Υ	Υ	1C7Q2AA	
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA/AT	
	NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC	Υ	Y	436M8AA	1
	HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	Υ	Υ	860T8AA	
	HP 25GbE SFP28 LC Fiber Optic Transceiver	Υ	Υ	860T9AA	
	Intel Ethernet I350-T4 4-Port 1Gb NIC	N	Υ	W8X25AA	
HP Remote System Controller		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Remote System Controller	Υ	Υ	7K6D7AA	
	HP Remote System Controller Main Board Adapter	Υ	Υ	7K6D8AA	
	HP Integrated Remote System Controller	Υ	Υ	7K6D9AA	
	HP Remote System Controller for Universal KVM	N	Υ	7K7N2AA	
Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Z4 Rack Rail Rack Kit	Υ	Υ	16G60AA/AT	
	HP Z4 Rack Front Bezel	Υ	Υ	16G58AA/AT	
	HP Z4 Rack Remote System Controller Support Bracket	Υ	N	8D0Q8AA	1
	HP Rack Cable Management Arm	N	Υ	35Z34AA	
	Note 1: This offering is a bracket to support the HP Re	emote System	Controller.		
Input Devices		Factory Configured	Option Kit	Option Kit Part Number	



Supported Components

HP Wired 320M Mouse Y 9VA80AA/ET/UT

NOTE: Keyboard and Mouse are optional or add on features.

Other Hardware		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Internal Serial Port and PS/2 Port	Υ	Υ	141K9AA/AT	
	HP Z4 Rack Dual PCIe Slot Riser Kit	Υ	Υ	7K6C7AA	
	HP Serial Port v3 Flex IO	Υ	Υ	5B895AA	
	HP Z4 Rack 2.5 in Drive Carrier	Υ	Υ	7K6C3AA	1
	HP Z4 Rack G5 2.5 in Dual Drive Cage Adapter	Υ	Υ	7K6C5AA	1
	HP Z4 Rack G5 3.5 in Drive Cage Adapter	Υ	Υ	7K6C6AA	1
	HP Internal USB Port Kit	N	Υ	EM165AA	
	HP Type-C SuperSpeed USB 20Gbps Front IO v2 Premium Module	Υ	Υ	38T92AA	
	C13 1.83m Power Cord Kit	N	Υ	6Z1T9AA	
	C13-C14 2.0m 15A 100-127V Countries Straight Desktop Power Cord	Υ	Υ	8R881AA	
	C13-C14 2.0m 10A 200-240V Countries Straight Desktop Power Cord	Υ	Υ	8R881AA	

Note 1: These carriers and adapters do not include storage devices. When ordering storage devices CTO, the necessary carrier or adapter is included. When ordering these carriers or adapters aftermarket, storage devices must be purchased separately.

Software	Factory Configured	Option Kit	Support Notes
Data Science Stack	Υ	N	1
WSL2/Ubuntu Data Science Stack	Υ	N	1
Note 1: Only available with Ubuntu and NVID	OIA® graphics.		



Supported Components

Operating Systems

Windows 11 Pro for Workstations 1,2

Ubuntu 22.04 LTS³ HP Linux®-ready

¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software, or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply, and additional requirements may apply over time for updates. See http://www.windows.com.

³ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software, or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for updates.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy,

HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Z4 Rack G5 Workstation into the enterprise, such as PXE, remote recovery, remote configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates –Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Class 3 UEFI specification version 2.7.
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information. Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery. Additional HP BIOS Features:
 - Power-On password Helps prevent an unauthorized user from powering on the system.



Supported Components

- Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated, and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - Power to expansion connectors / slots.
 - Most Wake events other than power buttons and WOL (Wake on LAN
 - supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled).
 - USB charging ports.

HP Sure Start Gen 7

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is executed and not rootkits, viruses, and malware. Verification is done upon boot up, shutdown and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking, and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e., system IDs), secure boot credentials, and other code the system needs to hoot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant 14

HP Image Assistant

HP Desktop Support Utility

HP Documentation

HP Notifications

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

HP Performance Advisor¹

myHP

HP Smart Health²¹

WSL/Ubuntu Data Science Stack

HP Privacy Settings

Touchpoint Customizer for Commercial

Kingsoft WPS Office

HP Services Scan²⁴

Manageability Features

HP Driver Packs²

HP UWP Pack

HP System Software Manager (SSM)

HP Manageability Integration Kit Gen43

HP Smart Support⁵

HP Client Catalog (download)

HP Image Assistant (download)



Supported Components

HP Cloud Recovery

HP Client Management Script Library (download)

HP BIOSphere Gen6 13

Client Security Software

HP Client Security Suite Gen74 including: (including Credential Manager, HP Password Manager⁶, HP Spare Key)

HP Power On Authentication

Microsoft Defender⁷

Security Management

HP Secure Erase 16

HP Wolf Pro Security Edition (optional) 18

HP Platform Certificates

HP Wolf Security for Business²² Includes:

HP Sure Click¹¹

HP Sure Sense¹²

HP Sure Run Gen59

HP Sure Recover Gen4 10

HP Sure Start Gen78

HP Tamper Lock

HP Sure Admin 17

HP Client Security Manager Gen 74

HP Security Update Service

- ¹ HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: https://www.hp.com/us-en/workstations/performanceadvisor.html
- ² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- ³ HP Manageability Integration Kit can be downloaded from https://ftp.ext.hp.com/pub/caps-softpag/cmit/HPMIK.html
- ⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.
- ⁵ HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- ⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- ⁷ Microsoft Defender Opt in and internet connection required for updates.
- ⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.
- ⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
- ¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- 11 HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- ¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- ¹³ HP BIOSphere Gen6 features may vary depending on the platform and configurations.
- ¹⁴ HP Support Assistant requires Windows and Internet access.
- ¹⁶ Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane.



Supported Components

¹⁷ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year, 3-year, 4-year, or 5-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.

²¹ HP Smart Health automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.

²² HP Wolf Security for Business requires Windows 10 or 11 or or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features.

²³ Kingsoft WPS office is only available in China.

²⁴ HP Services Scan is provided with Windows Update on select products and will check entitlement on each hardware device to determine if an HP TechPulse-enabled service has been purchased, and will download applicable software automatically. HP TechPulse is a telemetry and analytics platform that provides critical data around devices and applications. For full system requirements or to disable this feature, please visit http://www.hpdaas.com/requirements. Not applicable in China.



System Technical Specifications

System Board

Processor Socket Single LGA-4677 **CPU Bus Speed** DMI Gen4 x 8 lanes

Chipset Intel W790 Alder Lake – WS PCH

Super I/O Controller Nuvoton SIO21 **Memory Expansion Slots** 4 DDR5 memory slots

Memory Type Supported DDR5, RDIMM (Registered) ECC

Memory Modes Non- Interleaved for single channel. Interleaved when multiple channels are populated

Memory Speed Supported 4800MT/s for 1DPC

Memory ProtectionECC on dataMaximum Memory256GB

Memory Configuration 16GB, 32GB and 64GB RDIMMs are supported.

(Supported) (64GB RDIMM cannot be mixed with other module capacities in the same system)

NVDIMM Memory No

PCI Express Connectors Standard PCIe Slots

• 1 PCI Express Gen5 slot x16 mechanical/ x16 electrical (full height, full length)

Optional PCIe Slots

1 PCI Express Gen5 slot x16 mechanical/ x16 electrical (full height, full length)¹
 1 PCI Express Gen5 slot x16 mechanical/ x8 electrical (full height, full length)

¹ Slot 2 operates as x8 electrically if slot 3 is populated

M.2 Slots:

• 2 PCI Express Gen4 slot x4.

Other PCIe Connections

• 2 external 2.5" bays support 2 additional NVMe SSDs drives

• 1 external 3.5" bay (can be configured with 1 x 3.5" hard drive or 2 x 2.5" adapter for supporting 2

additional M.2 drives)

Supported Drive Interfaces SATA Number of SATA ports: 1

Intel® SATA controller: primary SATA

Integrated RAID On-board RAID Support:

Intel® VROC® SATA RAID 0, 1, 5, and 10 supported on Windows 10 and

11, RHEL 8.6 and later, SLE 15 SP4 and later

Intel® VROC® NVMe RAID 0, 1, 5, and 10 supported with presence of appropriate VROC upgrade module (after-market kits) on Windows 10

and 11, RHEL 8.6 and later, SLE 15 SP4 and later

Factory Configured RAID: None

Integrated Graphics No

Network Controller Intel WGI219LM

WGI219LM LOM provides Management capabilities: WOL, PXE 2.1, and

AMT 16.10

External SATA (eSATA) No

Serial Available with optional Flex I/O module

2nd Serial No **HD Integrated Audio** Yes

USB Connector(s) Front Front I/O Entry:

4 USB 3.1 Gen1 Type-A (left-most port supports Battery Charging 1.2)

Front I/O Premium:

2x USB 3.2 Gen2x2 Type-C[™] (Power Delivery 3.0)



System Technical Specifications

2x USB 3.1 Gen1 Type-A (left-most port supports Battery Charging

• USB Type-C Ports provide 3 Amps @ 5 Volts

• Charging USB Type-A port provides 1.5 Amps @ 5 Volts • Standard USB Type-A Ports provide 900mA @ 5 Volts

Rear 2x USB 3.1 Gen1 Type-A

Internal 1 USB 3.2 Gen1 header, with a single 12-pin shrouded connector. This

header supports a USB Media Card reader.

1 USB 2.0 single port header 1 USB 2.0 dual port header

Flash ROM Yes **CPU Fan Header** Yes **Fan Headers** Yes **Front Control** Yes Panel/Speaker Header

CMOS Battery Holder -Yes

Lithium

Integrated Trusted Integrated TPM 2.0.

Platform Module Convertible to FIPS 140-2 Certified Mode through firmware v15.22.

The TPM module is disabled where restricted by law.

Power Supply Headers Yes Power Switch, Power LED Yes & Hard Drive LED Header **Clear Password Jumper** Yes **USB** Keyboard/Mouse

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 11 Professional 64 bit, Red Hat Linux 64-bit.

²M.2 storage supports compatible devices up to 80mm



System Technical Specifications

System Configurati	ons								
Z4 Rack G5 Example	Processor Info	Intel Xeon W3	-2423 6C 4GH	Z					
Configuration #1	Memory Info	1x16GB DDR5	4800 (Registe	red DIMM)					
	Graphics Info	NVIDIA T400 4GB							
	Disks/Optical/Floppy	1x ZTurbo 512 GB TLC SSD							
	PSU	1x 675W							
Other N/A									
Energy Consumption		115	VAC	230	VAC	100	VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	67.225	66.464	67.534	66.684	67.223	66.461		
	Windows Busy Typ (S0)	163.043 160.88		163.036					
	Windows Busy Max (S0)	179.889		173.248		179.882			
	Sleep (S3)	3.658	3.547	3.662	3.549	3.654	3.542		
	Off (S5)	2.294	2.282	2.296	2.284	2.292	2.281		
	Zero Power Mode (EuP)	0.29 0.292			292	0.289			
Heat Dissipation		115	VAC	230	VAC	100	VAC		
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	229.371	226.775	230.426	227.528	229.365	226.764		
	Windows Busy Typ (S0)	556	.302	548	.923	556	.278		
	Windows Busy Max (S0)	1613	3.781	291	.122	613	.757		
	Sleep (S3)	12.481	12.102	12.494	12.109	12.467	12.085		
	Off (S5)	7.827	7.786	7.833	7.793	7.82	7.782		
	Zero Power Mode (EuP)	0.9	989	0.9	96	0.9	986		
Z4 Rack G5 Example	Processor Info	Intel Xeon W5	5-2445 10C 4.3	GHz					
Configuration #2	Memory Info	2x16GB DDR	5 4800 (Regist	ered DIMM)					
	Graphics Info	NVIDIA A2000	12GB						
	Disks/Optical/Floppy	1x ZTurbo 51	2 GB TLC SSD;	1x 1TB 7200 S	ATA Enterprise	3.5" HDD			
	PSU	1x 675W							
	Other	N/A							

	PSU	1x 675W						
	Other	N/A						
Energy Consumption (Watts)		115	115 VAC		230 VAC		100 VAC	
		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	73.476	72.395	73.668	72.597	73.473	72.389	
	Windows Busy Typ (S0)	304.743		299.685		303.156		
	Windows Busy Max (S0)	322.705		314.841		321.876		
	Sleep (S3)	3.718	3.509	3.723	3.515	3.716	3.505	
	Off (S5)	2.256	2.252	2.261	2.254	2.254	2.251	
	Zero Power Mode (EuP)	0.2	193	0.2	94	0.2	92	

Heat Dissipation	11	115 VAC		230 VAC		VAC
(Btu/hr)	LAN	LAN	LAN	LAN	LAN	LAN
	Enabled	Disabled	Enabled	Disabled	Enabled	Disabled



System Technical Specifications

	Windows Idle (S0)	250.700	247.012	251.355	247.701	250.689	246.991
	Windows Busy Typ (S0)	1039	9.783	1022	2.525	1034	1.368
	Windows Busy Max (S0)	1101	.069	1074	1.237	1098	3.241
	Sleep (S3)	12.685	11.972	12.702	11.993	12.678	11.959
	Off (S5)	7.697	7.683	7.714	7.690	7.690	7.680
	Zero Power Mode (EuP)	0.9	99	1.0	003	0.9	96
Z4 Rack G5 Example	Processor Info	Intel Xeon W	5-2555X 12C 4	.4GHz			
Configuration #3	Memory Info	2x32GB DDR	5 4800 (Regist	ered DIMM)			
	Graphics Info	NVIDIA A4000) 16GB				
	Disks/Optical/Floppy	1x ZTurbo 2T	B TLC SSD; 1x	4TB 7200 SAT	A Enterprise 3	.5" HDD	
	PSU	2x 675W					
	Other	N/A					

Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	83.416	81.931	83.647	82.004	83.412	81.928
	Windows Busy Typ (S0)	40	2.7	394	1.72	401	1.24
	Windows Busy Max (S0)	45	4.3	424	.337	452	2.64
	Sleep (S3)	4.827	4.653	4.833	4.658	4.824	4.649
	Off (S5)	2.695	2.688	2.704	2.691	2.691	2.686
	Zero Power Mode (EuP)	0.5	561	0.5	564	0.5	560

Heat Dissipation		115	VAC	230	VAC	100	VAC
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	284.615	c279.648	285.403	279.797	284.601	279.538
	Windows Busy Typ (S0)	1374	1.012	1346	5.785	1369	0.031
	Windows Busy Max (S0)	1550).072	1447	'.838	1544	1.408
	Sleep (S3)	16.469	15.876	16.490	15.893	16.459	16.469
	Off (S5)	9.195	9.171	9.226	9.182	9.181	9.195
	Zero Power Mode (EuP)	1.9	914	1.9)24	1.9	10

Z4 Rack G5 Example	Processor Info	Intel Xeon W7-2495X 24C 4.6GHz	TBD
Configuration #4	Memory Info	4x16GB DDR5 4800 (Registered DIMM)	TBD
	Graphics Info	NVIDIA A6000 48G	TBD
	Disks/Optical/Floppy	2x ZTurbo 2TB TLC SSD; 1x 8TB 7200 SATA Enterprise 3.5" HDD	TBD
	PSU	2x 675W	TBD
	Other	N/A	TBD

Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows dle (S0)	103.967	100.076	104.268	100.384	103.960	100.058
	Windows Busy Typ (S0)	627	.703	610).67	626	.938
	Windows Busy Max (S0)	594	1.57	57	7.2	593	.86
	Sleep (S3)	4.855	4.766	4.864	4.771	4.853	4.762

System Technical Specifications

Off (S5)	2.717	2.706	2.722	2.708	2.716	2.704
Zero Power Mode (EuP)	0.5	64	0.5	67	0.5	63

Heat Dissipation		115	VAC	230	VAC	100	VAC
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	354.735	341.459	355.762	342.510	354.711	341.397
	Windows Busy Typ (S0)	214	1.723	2083	3.606	2139	9.112
	Windows Busy Max (S0)	2028	3.673	1969	9.406	202	6.25
	Sleep (S3)	16.562	16.261	16.595	16.278	16.558	16.247
	Off (S5)	9.270	9.232	9.287	9.239	9.266	9.226
	Zero Power Mode (EuP)	1.9	924	1.9	34	1.9	920

NOTE: The numbers in this table are from actual measurements on a single system. There will be some variation from unit to unit.

NOTE: The busy power number and associated BTU/hr number for each configuration will be a strong function of the actual application software run on the system. There can be a great deal of variation in this number.

Yes, with Wake-on-LAN disabled: <1W in S5 - Power Off

NOTE: The Power Supply Efficiency report may be found at the following links: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

Operating Voltage Range 90-269 VAC **Rated Voltage Range** 100-240 VAC **Rated Line Frequency** 50-60 Hz **Operating Line Frequency** 47-66 Hz

Range

ENERGY STAR® certified Yes

(Config Dependent)

CECP Compliant @ 220V Yes

FEMP Standby Power

Compliant

Built-in Self-Test (BIST) Yes

LED

Surge Tolerant Full Yes

Ranging Power Supply (withstands power surges

up to 2000V)

Hood Lock Header Yes ErP Lot 6- Tier 1 Yes **Compliance @ 230V** (<1W

in S5 - Power Off)

ErP Lot 6- Tier 2 Yes

Compliance @ 230V (<0.5W in S5 - Power Off)

Declared Noise Emission	ıs	
System Configuration	Processor Info	Intel Xeon W3-2423 6C 4GHz
(Entry level)	Memory Info	1x16GB DDR5 4800 (Registered DIMM)
	Graphics Info	NVIDIA T400 4GB



System Technical Specifications

	Disks/Optical	1x ZTurbo 512 GB TLC SSD; 1x 2TB 7200 S	ATA Enterprise 3.5" HDD
	Power Supply	1x 675W	
Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)
7779 and ISO 9296)	Idle	5.1	36
	Hard drive Operating (random reads)	5.1	36

NOTE: Higher noise levels may be experienced with non-HP approved graphic card(s). Some consumer graphics cards have side blowing fans that may heat up thermal sensor(s) on the mother board causing fans to ramp.



System Technical Specifications

ENVIRONMENTAL DATA

Environmental Requirements **Temperature** Operating: 5° to 40°C (40° to 104°F)¹

Non-operating: -40° to 60°C (-40° to 140°F)

140°C has been validated for (add configuration information)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation

Maximum rate of change: 10 °C/hr No direct sustained sunlight

Humidity Operating: 8% to 85% relative humidity, non-condensing, 35° C maximum

wet bulb

Non-operating: 8% to 90% relative humidity, non-condensing, 35° C

maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

Shock (non-repetitive) Operating: ½-sine: 40g, 2-3ms (~62 cm/sec)

Non-operating: 1/2-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20g

Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025g²/Hz Non-operating

random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz **NOTE:** Values do not indicate continuous vibration.

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information.

Hard Drive Screw-mounted

Expansion Cards Expansion card cage removal/insertion into system is tool-less

Expansion card access requires removal of screw-mounted retainer bracket

Processor Socket Tool-less

Blue User Touch Points Yes, on primary serviceable components.

Color-coordinated Cables Yes

and Connectors

Memory DIMM Connectors Tool-less
System Board Screw-mounted

Dual Color Power/Failure Yes

LED

HDD Activity LED Yes

NOTE: HDD Activity LED is not dual color

Configuration Record SW Yes

Over-Temp Warning on Yes, at POST screen on reboot

Screen

Dual Function Front Power Switch

Padlock Support Yes (optional): Locks top cover and secures chassis from theft

7.0 mm (0.2756 in) diameter padlock loop at rear of system

Yes, causes a fail-safe power off when held for 4 seconds

Cable Lock Support Yes, Kensington Cable Lock (optional): Secures chassis from theft

3 mm x 7 mm slot at rear of system

Universal Chassis Clamp

Lock Support

Chassis Interlock Sensor Yes

Sensor detects when the access panel has been removed. The access panel must be installed for the

system to power ON.

Serial, USB, Audio,

Network, Enable/Disable

Port Control

Yes, enables or disables serial, USB, audio, and network ports

Removable Media Write/Boot Control Yes, prevents ability to boot from removable media on supported devices (and can disable writes to

media)

Power-On Password

Yes, prevents an unauthorized person from booting up the workstation

Setup Password

Yes, prevents an unauthorized person from changing the workstation configuration

3.3V Aux Power LED on

System PCA

Yes

NIC LEDs (integrated) (Green & Amber)

Yes

CPUs and Heatsinks

A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Power Supply Diagnostic Yes

LED **Front Power Button** Solid Green (OK); Blinking Green (Standby); Red (Fault); Off (No AC Power/PSU Failure)

Yes, ACPI multi-function

Rear Power Button Yes **System Locator LED** Yes, blue

Front Power LED Yes, white (normal), red (fault)

Yes

Front Hard Drive Activity Yes, white

LED

Internal Speaker

System/Emergency ROM

Flash Recovery

Recovers corrupted system BIOS.

Cooling Solutions Air cooled forced convection heatsinks **Power Supply Fan** 40 mm x 40 mm x 28 mm (non-serviceable) **Chassis Fans** 40 mm x 40 mm x 56 mm (serviceable)

HP PC Hardware Diagnostics UEFI HP PC Hardware Diagnostics (UEFI) enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing ESC then F2 upon the PC reboot and is

available as a download from HP Support.

Access Panel Key Lock

ACPI-Ready Hardware

Advanced Configuration and Power Management Interface (ACPI).

- Allows the system to wake from a low-power mode.
- Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system

Trusted Platform Module TPM Specification Version 2.0 (Infineon SLB 9672).

Chip

Common Criteria EAL4+ certified.

FIPS 140-2 Certification

TCG TPM Certified products list: http://www.trustedcomputinggroup.org/certification/tpm-certified-

products/

Integrated Chassis

Handles

No

Power Supply

Tool-less



PCIe Card Retention Yes, rear (all), middle (all), front (full-length cards with extender)

Flash ROM Yes **Diagnostic Power Switch** Yes

LED on board

Clear Password Jumper Yes
Clear CMOS Button Yes
CMOS Battery Holder Yes
DIMM Connectors Yes

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR. California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uk-en/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpuk-mu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics

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Please contact techregshelp@hp.com

(III)

BIOS

PCIe 5.0 Support Full BIOS support for PCI Express through industry standard interfaces. Supported speeds and slot

information vary.

AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b ATA/ATAPI

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is WMI Support

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Power On Users can define a specific date and time for the system to power on.

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM

Flash Recovery with Video

Recovers system BIOS in corrupted Flash ROM.

Replicated Setup

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

System Management BIOS Reference Specification, Version 3.2 **SMBIOS**

Boot Control Disables the ability to boot from removable media on supported devices.

Memory Change Alert Thermal Alert

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash

ACPI (Advanced

Allows the system to enter and resume from low power modes (sleep states).

Provides secure, fail-safe ROM image management from a central network console.

Configuration and Power Management Interface)

Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC (Suspend to RAM - ACPI

sleep state S3)

Allows for very low power consumption with quick resume time.

Remote System **Installation via F12 (PXE** operating system.

2.1) (Remote Boot from Server)

Allows a new or existing system to boot over the network and download software, including the

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.

Start-up Diagnostics (Power-on Self-Test) Auto Setup when new Assesses system health at boot time with selectable levels of testing.

hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.



System Technical Specifications

Localized ROM Setup Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with

local keyboard mappings.

Asset Tag The user or MIS to set a unique tag string in non-volatile memory.

Per-slot Control Allows I/O slot parameters (option ROM enable/disable, bifurcation, speed) to be configured

individually.

Adaptive CoolingControl parameters are set according to detected hardware configuration for optimal acoustics. **Pre-boot Diagnostics**(Pre-video) critical errors are reported via beeps and blinks on the power LED.

UEFI Specification

Revision

2.7

ACPI Advanced Configuration and Power Management Interface, Version 6.0

PCI Express Base Specification, Revision 2.0

PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0 PCI Express Base Specification, Revision 5.0

SATA Serial ATA Specification, Revision 1.0a

Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD JEDEC JESD300-5

TPM Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9672).

Common Criteria EAL4+ certified.

FIPS 140-2 Certification

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification USB Battery Charging specification, Revision 1.2 USB Power Delivery specification Revision 3.0

SMBIOS System Management BIOS Reference Specification, Version 3.2



Social and Environmental Responsibility

& Declarations

Eco-Label Certifications This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- **US ENERGY STAR®**
- US Federal Energy Management Program (FEMP)
- EPEAT® Gold with Climate+ registered. See www.epeat.net for registration status and tier levels by country
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact **Specifications**

- Product Carbon Footprint (hp.com)
- 25% post-consumer recycled plastic
- 10% recycled metal
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable
- **Recycled Plastic cushions**

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Workstation model is based on a "Typically Configured Workstation".

Energy Consumption (in accordance with US

ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	113.1 W	115.3 W	N/A
Normal Operation (Long idle)	109.1 W	110.1 W	N/A
Sleep	8.3 W	8.4 W	N/A
Off	2.8 W	2.9 W	N/A

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	386.80 BTU/hr	394.33 BTU/hr	N/A
Normal Operation (Long idle)	373.12 BTU/hr	376.54 BTU/hr	N/A
Sleep	28.39 BTU/hr	28.73 BTU/hr	N/A
Off	9.58 BTU/hr	9.92 BTU/hr	N/A

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Longevity and **Upgrading**

This product can be upgraded, possibly extending its useful life by several years.



System Technical Specifications

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive -2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 91.9% recycle-able when properly disposed of at end of life.

Packaging Materials

External:PAPER/Corrugated3984 gInternal:PLASTIC/EPE (Expanded Polyethylene)440 gPLASTIC/Polyethylene low density52 gPAPER/Molded Pulp1694 g

The plastic packaging material contains at least 0.0% recycled content.

The corrugated paper packaging materials contains at least 35.0% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/qlobalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzvl butvl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes



- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.

System Technical Specifications

- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.
- Plastic cushions are made from >90% recycled plastic.
- Recycled metal is expressed as a percentage of the total weight of the metal according to ISO 14021 definitions for metal parts over 25 grams



Manageability

Industry Standard Specifications Intel® Active Management Technology (AMT) This product meets the following industry standard specifications for manageability functionality:

DASH 1.2 (via Intel[®] LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 16.10

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 16.10 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - o Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.2 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Yes, when configured with an Intel® vPro® supporting processor.

This product is fully compatible with the HP Remote System Controller. It can be configured CTO or added as an aftermarket option.

Intel® vPro® Technology HP Remote System Controller

Stable & Consistent Offerings

Stable & Consistent Offerings

Global Series SKUs

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

Stable & Consistent Offerings

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors	Product #	Offering
	709P2AV	Intel Xeon W3-2423
	709P4AV	Intel Xeon W3-2435
Storage	Product #	Offering
Storage	Product # 708L4AV	Offering Z Turbo 1TB PCIe-4x4 2280 TLC M.2 Solid State Drive



Technical Specifications – Storage Drives

STORAGE/HARD DRIVES

Performance PCIe SSDs for HP Workstations

Z Turbo 512GB 2280 PCIe-4x4 TLC SSD

Capacity 512GB **Protocol PCIe** Form Factor M.2 Controller NVMe 3D TLC NAND Type

300TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Nο

Performance Sequential Read up to 6400MB/s*

> **Sequential Write** up to 3400MB/s* **Random Read** up to 600K IOPS* **Random Write** up to 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD** Capacity 512GB Protocol **PCIe Form Factor** M.2 NVMe Controller 3D TLC NAND Type

300TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6400MB/s*

> **Sequential Write** up to 3400MB/s* **Random Read** up to 600K IOPS* **Random Write** up to 600K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD** Module

1TB Capacity **PCle Protocol Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

^{*}Actual performance may vary.

Technical Specifications – Storage Drives

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read

Sequential Read up to 6500MB/s*
Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD

Capacity1TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 400TBW (TB Written)

No

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

PCI Express 4.0 x4 electrical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read

Sequential Read up to 6500MB/s*
Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD

Capacity 1TB
Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*



^{*}Actual performance may vary.

Technical Specifications – Storage Drives

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD**

2TB Capacity Protocol **PCIe Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Nο

Interface PCI Express 4.0 x4 electrical 32° to 158° F (0° to 70° C) Operating Temperature

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

Self-Encrypting Drive OPAL 2

Support

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 TLC SSD

2TB Capacity **Protocol PCIe Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

500TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 4TB 2280 PCIe-4x4 TLC M.2

SSD

Capacity 4TB **PCle Protocol Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications – Storage Drives

Endurance 600TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 700K IOPS*
Random Write up to 700K IOPS*

HP Z4 Rack G5 Workstation

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD
 Capacity
 4TB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

PCI Express 4.0 x4 electrical mperature 32° to 158° F (0° to 70° C)

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Nο

Sequential Write up to 5000MB/s*
Random Read up to 700K IOPS*
Random Write up to 700K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB PCIe-4x4 Capacity TLC Z4/Z6 Kit SSD Protocol

Capacity512GBProtocolPCleForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 300TBW (TB Written)

No

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

PCI Express 4.0 x4 electrical 2° to 158° F (0° to 70° C)

^{*}Actual performance may vary.

Technical Specifications – Storage Drives

Performance	Sequential Read	up to 6400MB/s*
	Sequential Write	up to 3400MB/s*
	Random Read	up to 600K IOPS*
	Random Write	up to 600K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB 2280 Capacity
PCIe-4x4 SED OPAL2 TLC
M.2 Z4/Z6 Kit SSD Protocol

Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Nο

Performance Sequential Read up to 6400MB/s*

Sequential Write up to 3400MB/s*
Random Read up to 600K IOPS*
Random Write up to 600K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB

Z Turbo 1TB PCIe-4x4 TLC Capacity Z4/Z6 Kit SSD Protocol

Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Capacity 1TB



^{*}Actual performance may vary.

Technical Specifications – Storage Drives

Z Turbo 1TB 2280 PCle-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD
 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCle-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD
 Capacity
 2TB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

OPAL 2

Self-Encrypting Drive

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 4TB 2280 PCle-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD Capacity4TBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M hours

Technical Specifications – Storage Drives

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequent

Sequential Read up to 6500MB/s*
Sequential Write up to 5000MB/s*

Random Read up to 700K IOPS*
Random Write up to 700K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

SATA Hard Drives for HP Workstations

1TB 7200RPM SATA 3.5in Capacity Enterprise HDD Protocol

Capacity 1TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability 2.0M hours
Rated Power On Hours 8760/vr

Annualized Failure Rate (based on Rated POH)

<0.62%

Rated for 24/7/365

operation

YES

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 128MB Cache Adaptive

Seek Time (typical reads, includes controller overhead, including Full Stroke 0.32 ms * 0.32 ms

settling)

Rotational Speed 7,200 rpm **Logical Blocks** 1,953,525,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB 7200RPM SATA 3.5in Capacity 2TB Enterprise HDD Protocol SATA



^{*}Actual performance may vary.

Technical Specifications – Storage Drives

Form Factor 3.5"
Controller AHCI
Reliability 2.0M hours
Rated Power On Hours 8760/yr
Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365 operation

YES

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

.

Buffer 128MB
Cache Adaptive
Seek Time (typical reads, Single Track

Seek Time (typical reads, includes controller overhead, including settling)

Average Full Stroke 0.7 ms * 8.5 ms *

i att stroke

15.7 ms *

Rotational Speed 7,200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB 7200 RPM SATA 3.5in Capacity 4TB
Enterprise HDD Protocol SATA

Form Factor 3.5"

Controller AHCI

Reliability 2.0M hours

Rated Power On Hours 8760/yr

Annualized Failure Rate <0.62%

(based on Rated POH)

Rated for 24/7/365

operation

YES

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer U

Rate (Maximum)

Up to 600MB/s *

Buffer 256MB Cache Adaptive

Single Track 0.7 ms *



Technical Specifications – Storage Drives

Seek Time (typical reads, Average 8.5 ms * includes controller **Full Stroke** 15.7 ms *

overhead, including

settling)

Rotational Speed 7,200 rpm **Logical Blocks** 7,814,037,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance up to 226MB/s* Sequential Read Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

8TB 7200RPM SATA 3.5in Capacity **Enterprise HDD**

Protocol SATA Form Factor 3.5" Controller **AHCI** Reliability 2.0M hours **Rated Power On Hours** 8760/yr

Annualized Failure Rate (based on Rated POH)

YES

< 0.62%

Rated for 24/7/365

operation

Height

1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 256MB Cache Adaptive

Seek Time (typical reads. includes controller overhead, including

Single Track

 $0.7 \, \text{ms} \, *$ Average 8.5 ms * **Full Stroke** 15.7 ms *

settling)

Rotational Speed 7,200 rpm **Logical Blocks** 15,628,053,168

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s* Sequential Write up to 226MB/s*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

12TB 7200 RPM SATA-6G Capacity 3.5in Enterprise HDD

12TB **Protocol** SATA Form Factor 3.5" Controller AHCI Reliability 2.0M hours



^{*}Actual performance may vary.

 $0.7 \, \text{ms} \, *$

8.5 ms *

15.7 ms *

QuickSpecs

Technical Specifications – Storage Drives

Rated Power On Hours 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365

operation

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

YES

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

256MB Adaptive

Cache Adaptive

Seek Time (typical reads, includes controller overhead, including

settling)

Buffer

Rotational Speed 7,200 rpm Logical Blocks 23,437,770,752

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

Full Stroke

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



^{*}Actual performance may vary.

Technical Specifications - Graphics

GRAPHICS

NVIDIA® RTX™ 6000

Ada 48GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length) Weight: 1230 grams / 2.71 lbs (with extender)

Max Power Power: 300 Watts Consumption Cooling: Active

48GB GDDR6 memory ECC **GPU Memory**

Memory Bandwidth: Up to 960 GB/s

Memory Width: 384 bits

Connectors 4x DisplayPort 1.4a Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Maximum Resolution

Bus Type

7680x4320 @ 120Hz PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® RTX™ A6000

48GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Max Power Consumption Power: 300 Watts

Cooling: Active

48GB GDDR6 memory **GPU Memory**

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution

Bus Type

7680x4320 @ 120Hz

PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® RTX™ 5000 Ada Form Factor

32GB

Full-Height Dual Slot (4.4" Height x 13.85" Length)

Weight: 1130 grams / 2.49 lbs (excluding extender)

Max Power Consumption Power: 250 Watts

Cooling: Active

GPU Memory 32GB GDDR6 memory ECC

Memory Bandwidth: Up to 576 GB/s

Memory Width: 256 bits

4x DisplayPort 1.4a **Connectors**

Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Maximum Resolution 7680x4320 @ 120Hz



Technical Specifications - Graphics

Bus Type PCI Express 4.0 x16

Available Graphics

Drivers Windows 10

Linux® 64-bit

Windows 11

NVIDIA® RTX™ A5000

24GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Max Power Consumption Power: 230W

Cooling: Active

GPU Memory 24GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution 7680x4320 @ 120Hz

Bus Type PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX 4500 Ada

24GB

Form Factor

Full-Height Dual Slot (4.4" Height x 10.5" Length)

Max Power Consumption 210W

GPU Memory 24GB GDDR6

Memory Bandwidth: 432 GB/s Memory Width: 192-bit

Memory Width. 132 t

Connectors 4x DisplayPort 1.4a

Requires: 1x 16-pin CEM 5 power connector (adapter may be needed)

Maximum Resolution 4x @ 4096 x 2160 @ 120Hz

4x @ 5120 x 2880 @ 60Hz 2x @ 7680 x 4320 @ 60Hz

Bus Type PCI Exress 4.0 x16

Available Graphics Windows 10

Drivers Windows 11

NVIDIA® RTX A4500 20GB Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Max Power Consumption Power: 200W

Cooling: Active

GPU Memory 20GB GDDR6 memory

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

Technical Specifications - Graphics

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution

7680x4320 @ 120Hz PCI Express 4.0 x16

Bus Type

Available Graphics Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® RTX™ 4000 Ada Form Factor

Full-Height Single Slot (4.4" Height x 9.5" Length)

20GB

Max Power Consumption Power: 130W

Cooling: Active

GPU Memory

20GB GDDR6 memory

Memory Bandwidth: Up to 360 GB/s

Memory Width: 256 bit

Connectors

4x DisplayPort 1.4a

Requires 6-pin auxiliary power

Maximum Resolution

7680x4320 @ 120Hz

Bus Type

PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® RTX A4000 16GB Form Factor

Full-Height Single Slot (4.4" Height x 9.5" Length)

Weight: 500 grams

Max Power Consumption

Power: 140W Cooling: Active

GPU Memory

16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

Connectors

4x DisplayPort 1.4a

Quadro Sync II connector

Stereo Sync

Requires 6-pin auxiliary power

Maximum Resolution

Max Power Consumption

7680x4320 @ 120Hz

Bus Type

PCI Express 4.0 x16

Available Graphics

Windows 11

Drivers

Windows 10

Linux® 64-bit

AMD® Radeon™ Pro W6800 32GB

Form Factor Full-Height Dual Slot (4.4" Height x

10.5" Length)

Weight: 850 grams

Power: 261W Cooling: Active

Technical Specifications - Graphics

GPU Memory 32GB GDDR6 memory

Memory Bandwidth: Up to 512 GB/s

Memory Width: 256 bit

Connectors 6x mini-DisplayPort 1.4

Requires 8-pin+6-pin auxiliary power

Maximum Resolution 7680x4320 @ 60Hz

Bus Type PCI Express 4.0 x16

Available Graphics Windows 11

Drivers Windows 10 Linux® 64-bit

NVIDIA® RTX A2000 12GB Form Factor Half-Height Dual Slot (2.713"

Height x 6.6" Length) Weight: 306 grams

Max Power Consumption Power: 70W

Cooling: Active

GPU Memory 12GB GDDR6 memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192 bit

Connectors 4x mini-DisplayPort 1.4a
Maximum Resolution 7680x4320 @ 120Hz
Bus Type PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® T1000 8GB Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length)

Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors4x mini-DisplayPort 1.4aMaximum Resolution7680x4320 @ 120HzBus TypePCI Express 3.0 x16

Available Graphics

Drivers Windows 10

Linux® 64-bit

Windows 11

NVIDIA® T1000 4GB Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Technical Specifications - Graphics

Connectors4x mini-DisplayPort 1.4aMaximum Resolution7680x4320 @ 120HzBus TypePCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® T400 4GB Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 123.5 grams

Max Power Consumption Power: 30W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 80 GB/s

Memory Width: 64 bit

Connectors3x mini-DisplayPort 1.4aMaximum Resolution7680x4320 @ 120HzBus TypePCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit



Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

HP 10GBase-T Flex Port Connector RJ-45 (Single Port)

Cabling Twisted Pair Cabling, up to 100 meters

Controller Marvell AQC113C

Memory 128KB Tx Buffer, 192KB Rx Buffer on-chip Data Rates Supported 10/100/1000 Mbps and 2.5/5/10 Gbps

Compliance 802.3 - 2018, 802.1AS-2011
Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (SO state) and SMBus for

host and management traffic

Power Requirement Requires 0.7V VDD, 1V, and 2V for analog, 3.3V for VDDIO

Boot ROM Support Yes

Network Transfer Mode Full-duplex **Network Transfer Rate** 10GBASE-T

5GBASE-T 2.5GBASE-T 1000BASE-T 100BASE-TX 10BASE-Te

Management Capabilities WOL, PXE, UEFI,

Kit Contents HP 10GBase-T Flex Port NIC Module

HP 2.5GbE LAN Flex Port Connector RJ45 (Single Port)

Cabling Copper twisted pair, Cat5e up to 100 meters

Controller Intel® I225-V

Memory 4 Tx and 4 Rx Queues, Jumbo Frames up to 9KB and without TSN

Data Rates Supported 10/100/1000Mbps and 2.5Gbps BASE-T

Compliance IEEE 802.3, 802.3u (auto-negotiation), 802.3ab, 1588, 802.1AS-Rev,

802.1Qav, 802.1Qbu, 802.1Qbv, 802.3br, 802.3az

Bus Architecture PCIe G2x1

Data Transfer Mode PCIe-based interface for active state operation (SO state) and SMBus for

host and management traffic (Sx low power state)

Power Requirements 2.2 Watts

Network Transfer Mode Automatic link configuration for speed duplex and flow control

Network Transfer Rate 2500BASE-T 1000BASE-T

1000BASE-TX (Half-duplex supported)

10BASE-TA (Half-duplex supported)

Management Capabilities WOL, PXE, UEFI, Intel vPro® support with appropriate Intel Chipset, Error

Correcting Memory in packet buffers, UDP/TCP/IP Checksum Offload, SCTP

receive and transmit integrity offload

Kit Contents HP 2.5GbE LAN Flex Port Networking Interface Card



Technical Specifications - Networking and Communications

Intel® X550 10GBASE-T **Dual Port NIC**

Connector 2 x RJ-45

Cabling Cat5 (or higher) for 100Mbps

> Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6 (or higher) for 10Gbps up to 55m Cat6a (or higher) for 10Gbps up to 100m

Controller Intel X550-AT2

Memory Jumbo Frames up to 15.5KB, 64 Tx and 64Rx Queues per port, 160KB/port

of programmable memory transmit buffers

Data Rates Supported

100Mbps (BASE-TX), 1Gbps (BASE-T, 2.5Gbps, 5Gbps, 10Gbps

Compliance

802.1q (VLAN), 802.1Qbb, 802.1p, 802.1Qaz

Bus Architecture PCIe 3x4

Data Transfer Mode PCIe Gen 3 x4 based interface

Power Requirements 3.9W at 100Mbps

5.5W at 1Gbps 11.2W at 10Gbps

Boot ROM Support Yes

Network Transfer Mode Auto negotiation between 1GbE, 2.5GbE, 5GbE and 10GbE

Management Capabilities DMI 2.0 Support, Windows Management Instrumentation (WMI) and SNMP,

PXE 2.0 through boot ROM, Multi-mode I/O Virtualization, VxLAN, VMDg,

VLAN support with VLAN tag insertion

Intel® X550 10GBASE-T Dual Port NIC **Kit Contents**

Allied Telesis AT-2914SX/LC 1GB LC Fiber NIC

Connector LC Fiber (Single Port)

50/125 µm (core/cladding) multimode fiber optic cable up to 500m Cabling

62.5/125 µm (core/cladding) multimode fiber optic cable up to 220m

Jumbo Frames up to 9.6KB Memory

Data Rates Supported

1000SX (1GbE Fiber at 850nm Wavelength)

Compliance IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC),

IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE

802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

PCle x1 **Bus Architecture**

Data Transfer Mode PCIe-based interface **Power Requirements** 1.5 Watts (typical)

Network Transfer Rate 1000SX only (1GbE Fiber at 850nm Wavelength)

Management Capabilities UEFI, Smart Load Balancing and failover, Link aggregation (IEEE802.3ad),

Generic trunking (FEC/GEC) / IEEE 802.3ad-draft static, VLAN Support

Allied Telesis AT-2914SX/LC 1GB LC Fiber NIC with low-profile bracket **Kit Contents**

attached and standard height bracket included

Allied Telesis AT-2911T/2-901 Dual Port **1GbE NIC**

Connector 2 x RJ-45 (Dual Port)

Cabling Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Memory 17 Rx and 16 Tx gueues 10/100/1000 Mbps **Data Rates Supported**



Technical Specifications - Networking and Communications

Compliance IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC),

IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation), IEEE 802.3ab

(10/100/1000T)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCle 2x1

Data Transfer ModePCIe-based interfacePower Requirements2.4 Watts (typical)

Management Capabilities VLAN support, Link aggregation LACP, Link aggregation smart switch,

Failover, Smart Load Balancing (SLB), iSCSI boot support, Windows

Management Instrumentation (WMI), PXE 2.1, SNMP

Kit Contents Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC with low-profile bracket

attached and standard bracket included

NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC Connector 2 x SFP28 Transceiver Cage (Dual Port)*

Cabling Depends on transceiver pairing. Typically OM4 or higher MMF LC fiber optic

cabling with LC SFP28 Transceivers.

Controller ConnectX6-DX

Memory 256Mbit SPI Quad Flash Device

Data Rates Supported 1/10/25GbE

Compliance – IEEE 802.3by 25 Gigabit Ethernet

- IEEE 802.3ae 10 Gigabit Ethernet

– IEEE 802.3ap based auto-negotiation and KR startup

– IEEE 802.3ad, 802.1AX Link Aggregation – IEEE 802.1Q, 802.1P VLAN tags and priority

- IEEE 802.1Qau (QCN)
- Congestion Notification
- IEEE 802.1Qaz (ETS)
- IEEE 802.1Qbb (PFC)
- IEEE 802.1Qbg
- IEEE 1588v2

Jumbo frame support (9.6KB)Safety: CB/cTUVus/CEEMC: CE/FCC/VCCI/RCMRoHS Compliant

- KCC

- CAN ICES-3 (B)

- NM EN 55035/55032 (Morocco)

- UKCA

Bus Architecture PCle Gen 4 x8

Data Transfer Mode PCI Express - stores and accesses Ethernet fabric connection information

and packet data

Power Requirements 11.5 Watts (typical)
Network Transfer Rate 1Gbps, 10Gbps, 25Gbps

NOTE: Network Transfer Rate depends on transceiver model.*

Kit Contents NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

Technical Specifications - Networking and Communications

HP 1GbE Fiber LC Single

Flex Port

Connector LC (Little Connector) Fiber (Single Port)

Cabling LC Fiber Cabling Controller AT-29M2 **Data Rates Supported** 1GBASE-SX **Bus Architecture** USB 3.1G1 **Power Requirements** Up to 3.3 Watts **Network Transfer Mode** 1GBASE-SX

Network Transfer Rate 1GBASE-SX Management

Capabilities Kit Contents Wake on LAN, Digital Diagnostic Monitoring

HP 1GbE Fiber LC Single Flex Port NIC

Intel® 1225-T1 Single Port 2.5GbE PCIe NIC

Connector RJ-45 (Single Port)

Cabling Cat5e (or better) up to 100m Intel® Ethernet I225 Controller Controller

Memory Jumbo Frames up to 9.5KB, 4 Tx and Rx Queues

2.5GbE, 1GbE, 100MbE, 10MbE **Data Rates Supported**

Compliance IEEE 802.3 auto negotiation, 802.3x, 802.3z **Bus Architecture** PCIe-based interface for active state operation **Data Transfer Mode** PCIe-based interface for active state operation

Power Requirements 1.9 Watts (typical)

Management **Capabilities**

Network Transfer Rate

WOL, PXE 2.1, Power Management Protocol Offload (proxying), MAC

Power Management, Active State Power Management

Intel I225-T1 1-Port 2.5GbE NIC with standard height bracket attached

and Low-profile bracket included Product Literature

Intel Ethernet 1350-T4V2 4-Port 1Gb NIC

4x RJ-45 (Quad Port) Connector

Cabling Cat3 (or higher) for 10Mbps Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Intel® I350 Controller

Jumbo Frames up to 9.5KB, 8 Tx/Rx Queue pairs per port, Main Internal Memory

memory is Error Code Correcting

Data Rates Supported Compliance

10Mbps, 100Mbps, 1Gbps

IEEE 802.3 auto negotiation, 802.3, 802.3u, 802.3ab, 802.3x, 802.3z,

IEEE1588 protocol and 802.1AS implementation, 802.3az EEE

Bus Architecture PCI Express 2.1 x4

Data Transfer Mode PCIe-based interface for active state operation

Power Requirements 5 Watts

Network Transfer Mode Multi-speed, full, and half-duplex

Network Transfer Rate 10BASE-T 100BASE-Tx

1000BASE-T

Management WOL, PXE 2.1, UEFI, Power Management Protocol Offload (proxying), MAC Capabilities Power Management, Active State Power Management, VLAN, ACPI **Kit Contents** Intel® Ethernet I350-T4V2 4-Port 1Gb NIC with full-height bracket

installed Low-profile bracket included

Date of change:	Version History:		Description of change:
September 5, 2023	From v1 to v2	Changed	Social and Environmental Responsibility section
September 25, 2023	From v2 to v3	Changed	SOFTWARE AND SECURITY section
November 1, 2023	From v3 to v4	Changed	Graphics, Software, System Board sections
December 1, 2023	From v4 to v5	Changed	Graphics, Other Hardware, Social and Environmental
			Responsibility sections
January 1, 2024	From v5 to v6	Changed	PCIe Solid State Drives section
February 1, 2024	From v6 to v7	Changed	STORAGE/HARD DRIVES, Graphics, Social and Environmental
			Responsibility sections
March 1, 2024	From v7 to v8	Changed	Rear View, Graphics and Declared Noise Emissions sections
April 1, 2024	From v8 to v9	Changed	Format

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